APPLICATION DATA SHEET

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Attorney Docket Number: 7808-US-PA

Publication Filing Type:

new-utility

Application Type:

utility

Title of Invention:

BUMP LAYOUT ON SILICON CHIP

Customer Number Attorney:

31561

Customer Number Correspondence Address:

31561

Foreign Priority:

90119108

TW

2001-08-06

Priority Claimed

INVENTOR(s):

Primary Citizenship:

TAIWAN

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